



TWSE

6515

Investor Presentation

• • • • • 2025.03.18

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WinWay's actual results or developments may differ materially from those indicated by these forward-looking statements as a result of various factors and uncertainties, including but not limited to market demand, price fluctuations, competition, change in legal, government policies, financial market conditions, and other risks and factors beyond our control.

This presentation does not undertake any obligation to publicly update any forward-looking statements to reflect events or circumstances after the date on which any such statement is made or to reflect the occurrence of unanticipated events.



Company Information

■ Founded

2001 / 4 / 10

■ Business Operation

Design, manufacture, sale and service
of test interface products

■ Chairman & CEO

Mark Wang

■ Capital Stock

NTD 350,153,320

■ Employees

986

■ Registered Address

No.68, Chuangyi S. Rd, Nanzi Dist.

Kaohsiung City, Taiwan

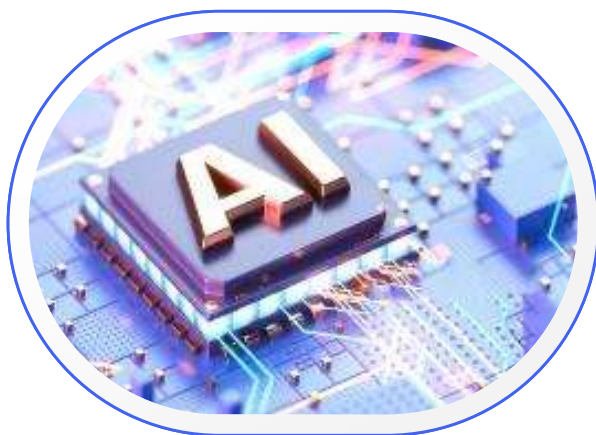


Kaohsiung Headquarter



**Hsinchu
Branch Office**

Company Vision



Innovation

We deliver the best possible test tooling solutions to our customers through technological innovation.



Quality

We exceed customers' quality requirements by offering cost-effective total solutions and on-time delivery worldwide.



Service

We strive to become the world's leading professional testing service provider in all phases of IC testing.

Agenda



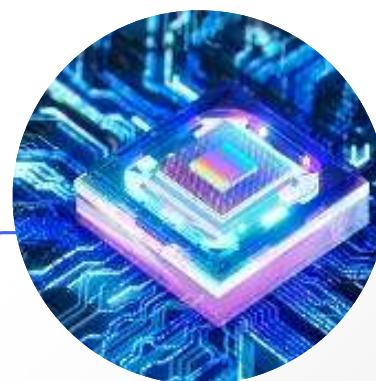
**Global
Presence**



**Industry
Trend**



**Financial
Performance**

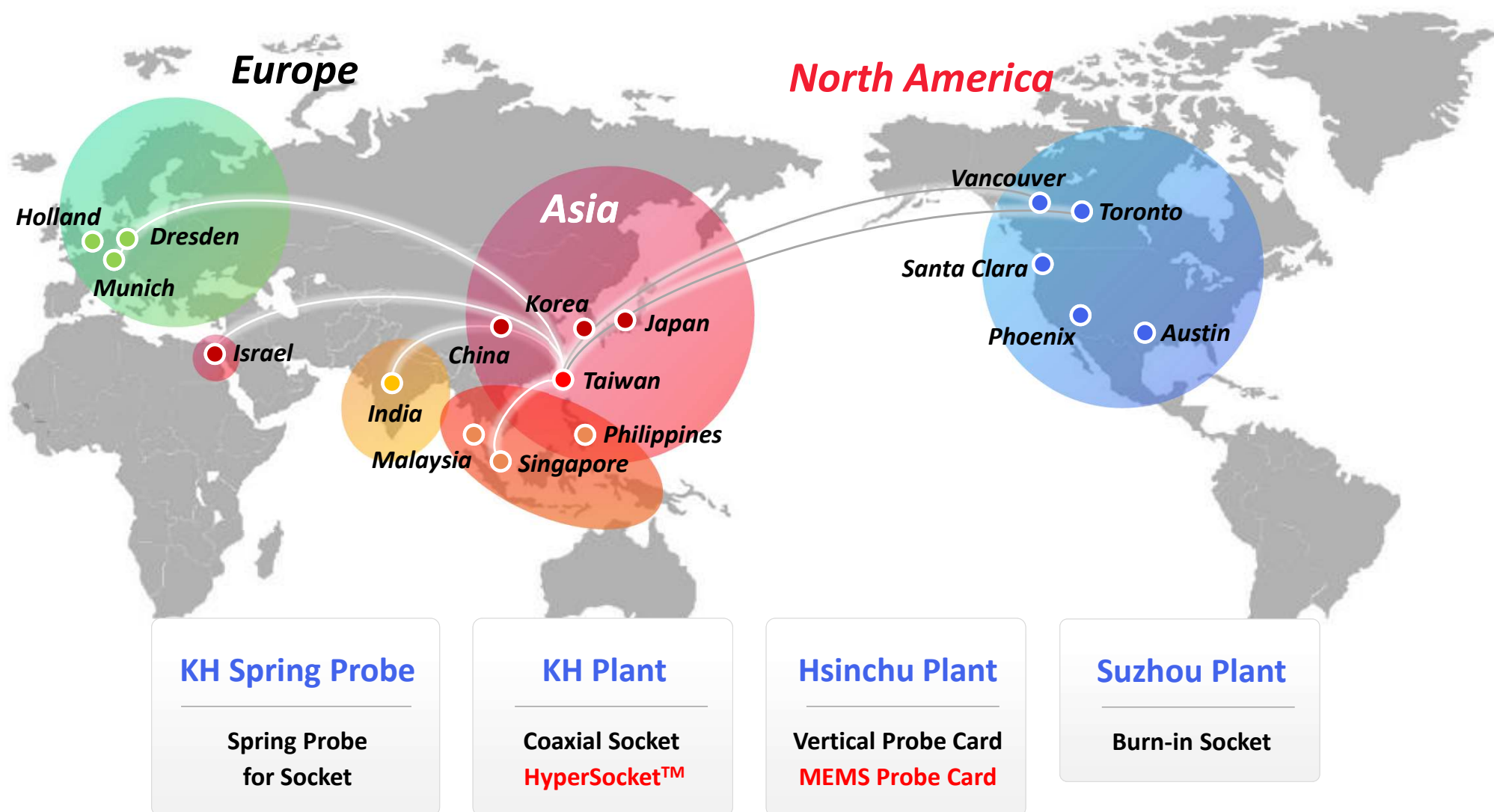


**R&D
Innovation**

01

Global Presence

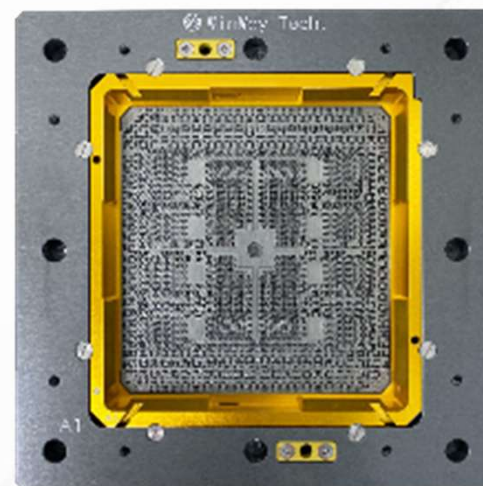
Global Service & Support Network



Semiconductor Test Interface Leadership

3

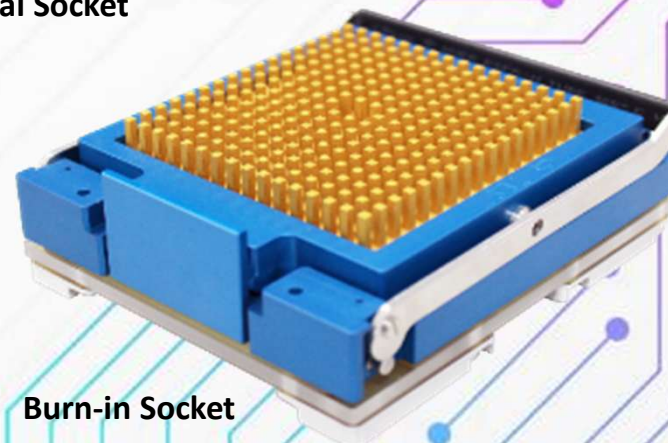
2023
Test Socket
Ranking



Coaxial Socket

5

2023
Test and Burn-in
Socket Ranking



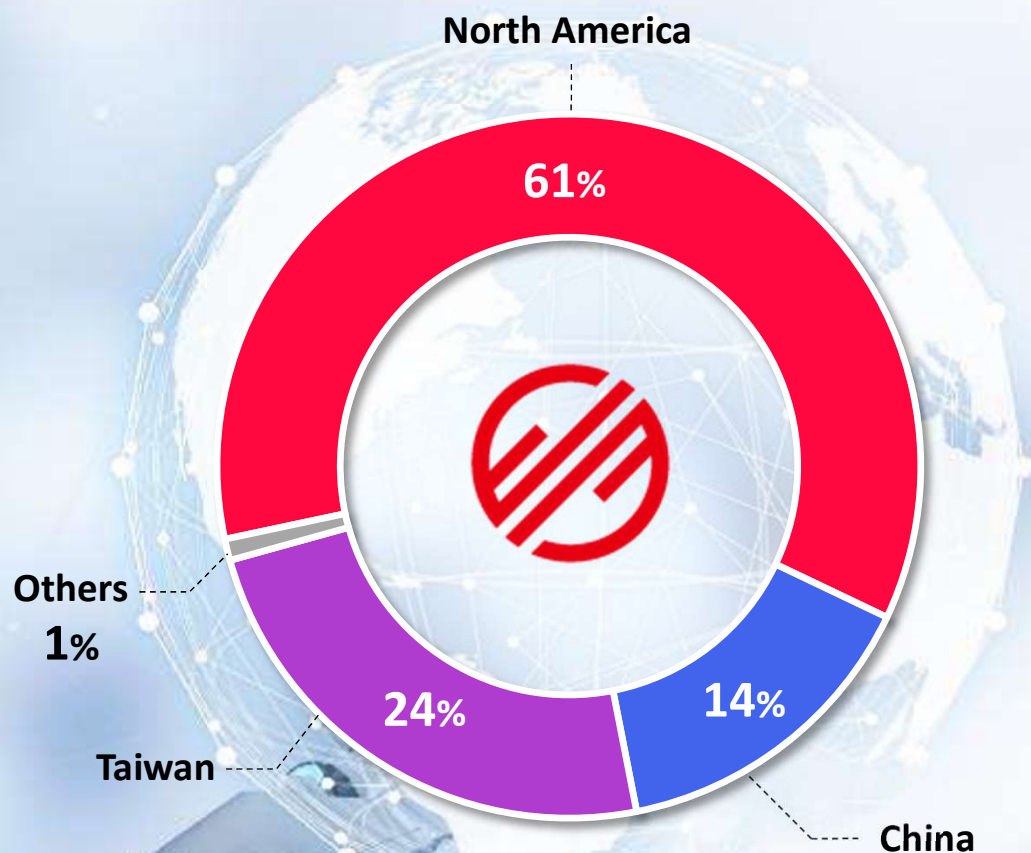
Burn-in Socket

22

2023
Probe Card
Ranking

Source: Yole Intelligence, 2024/04

Worldwide Customer



86% Top10 Customers

AI

AP

HPC

CPU

ASIC

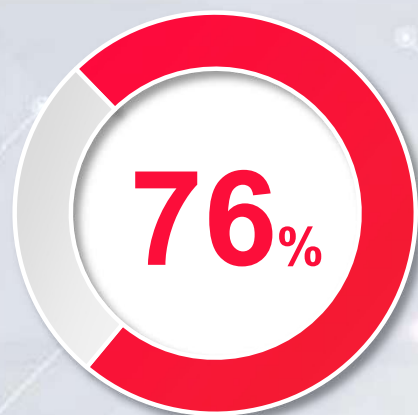
GPU

200⁺ Active Customers

- IC Design
- IDM
- CSP
- OSAT
- Foundry

Bolstered by Advanced Technology

(Year 2024)



Advanced Node



AI



HPC



GPU

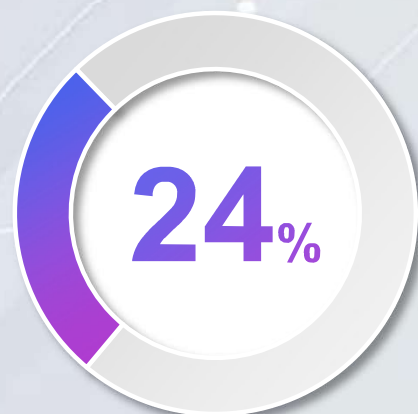


CPU



Smart Phone

7nm (or equivalent node) and below



Mature Node



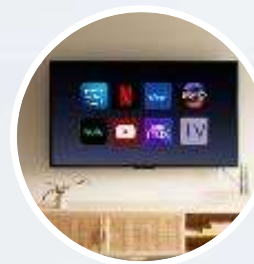
Automotive



Networking



IoT



DTV & STB



NAND Flash

02

Industry Trend

AI Semiconductor Mega-Trend

Global AI Economic Impact

\$19.9

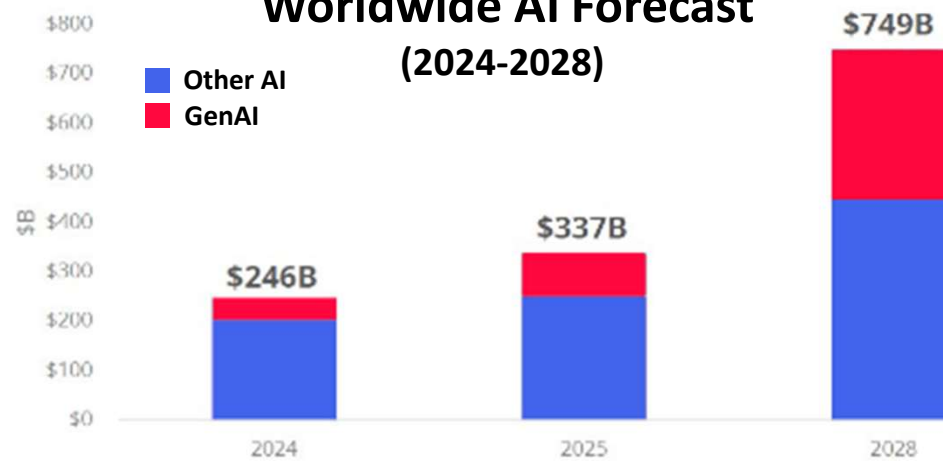
Trillion by 2030

Global GDP

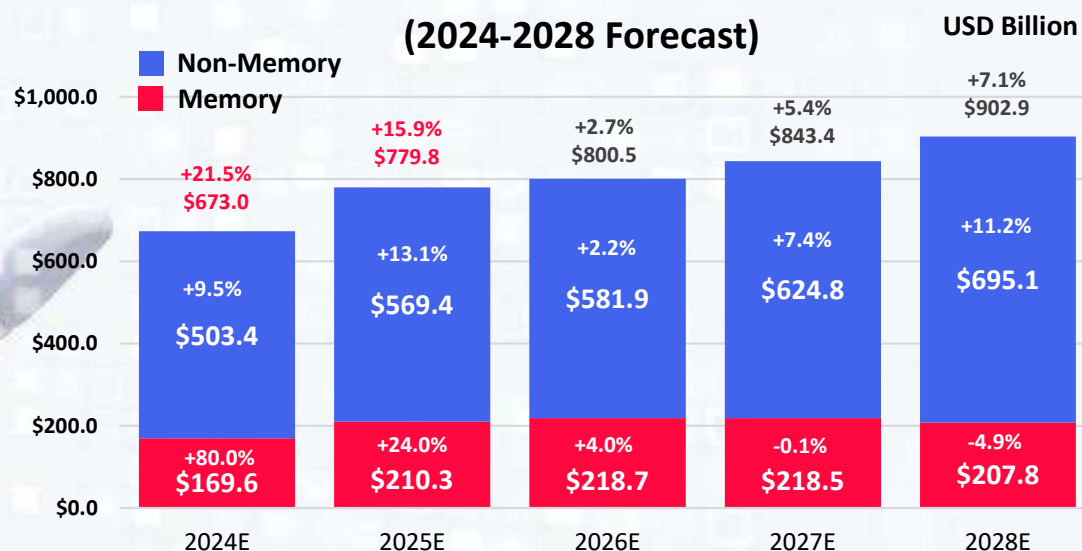
3.5%

Source : IDC, 2024

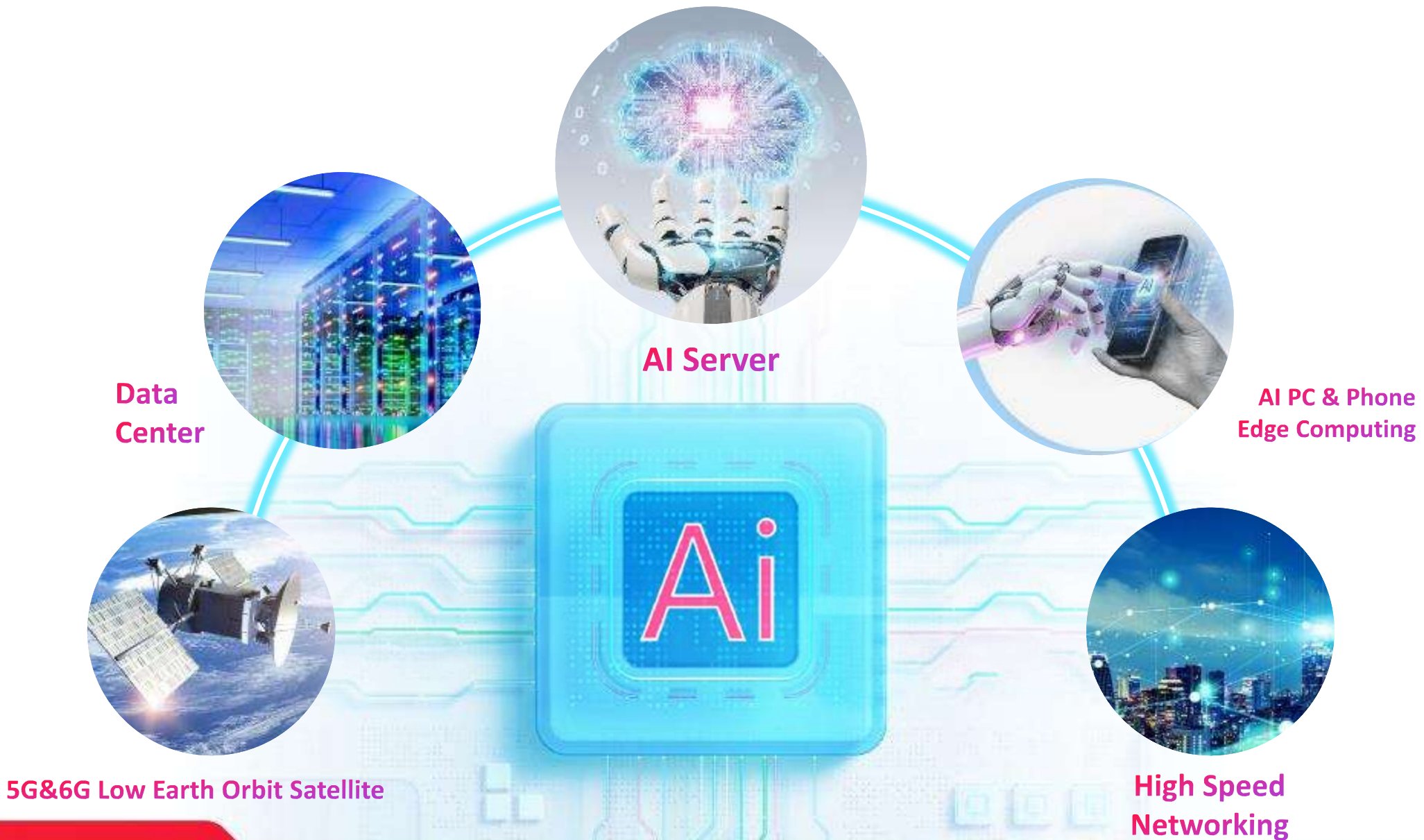
Worldwide AI Forecast (2024-2028)



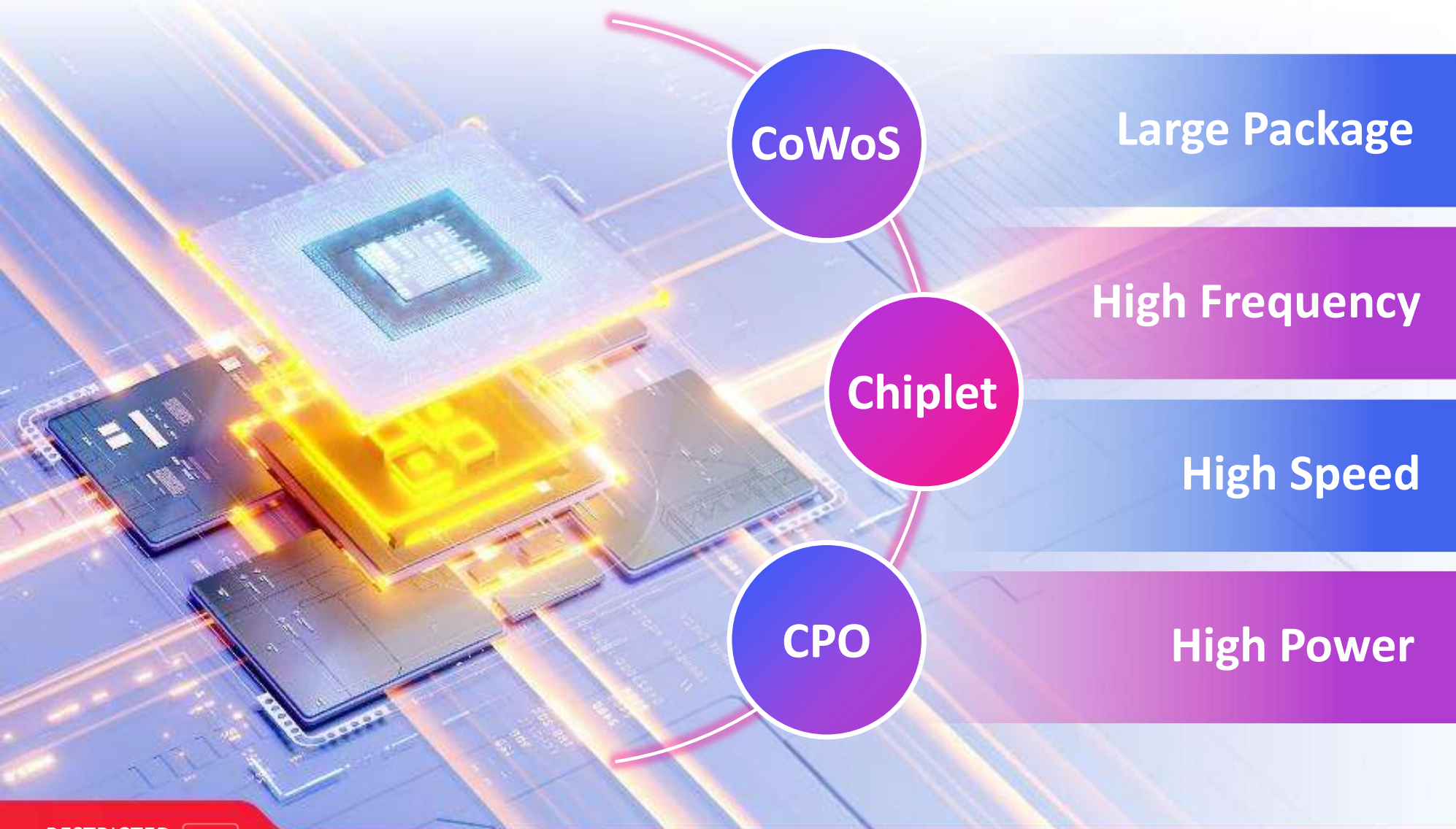
Semiconductor Total Market (2024-2028 Forecast)



Driving Force for AI

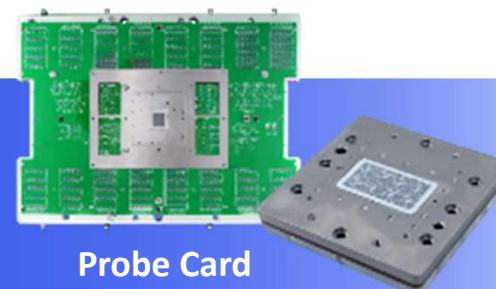


High Performance Testing Driven by Advanced Packaging



Total Solution for Semiconductor Test

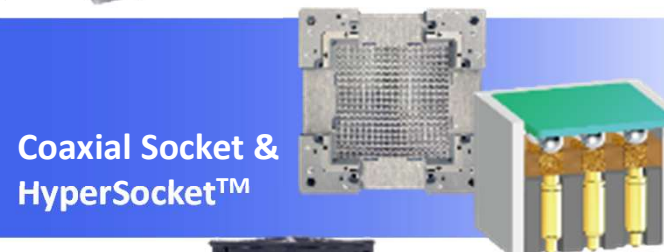
Wafer Sort
(CP - Circuit Probe)



Final Test
(Final Test)



SLT (System Level Test)
SFT



Functional Burn-in



DFT Design For Testing **DFM** Design For Manufacturing

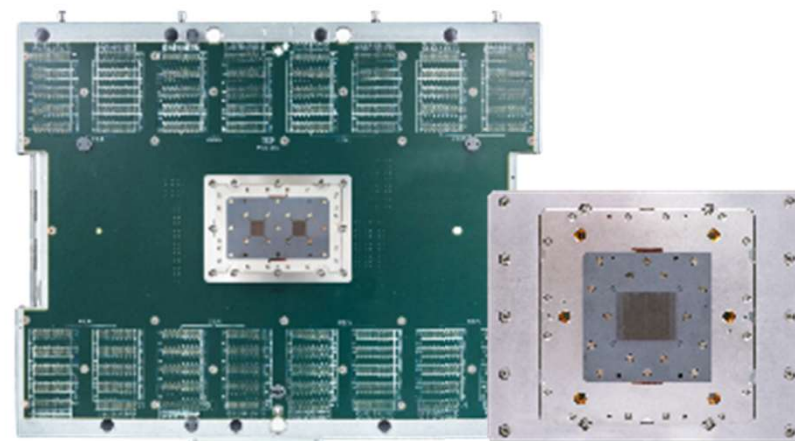
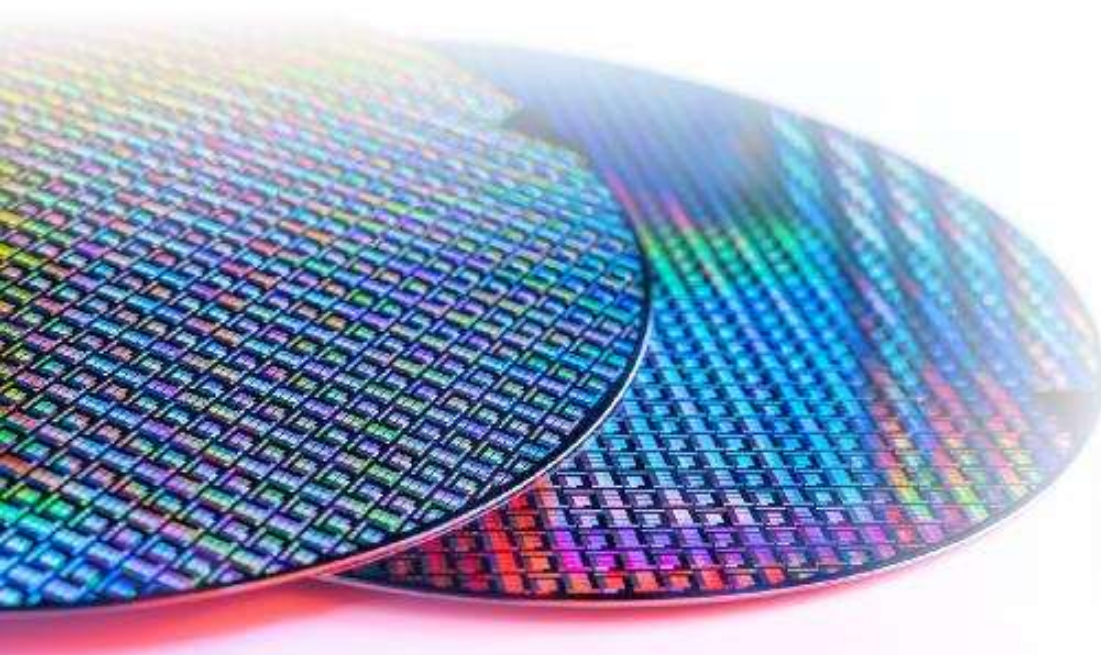
Greater Importance on Chip Probing

From Shadows to Spotlight

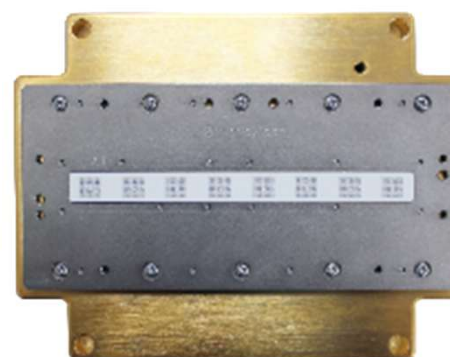
K.G.D

Close to
Known Good Die

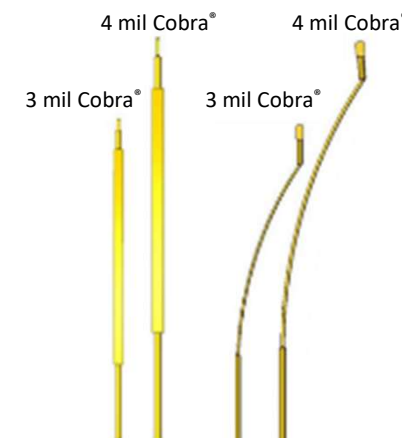
- CoWoS
- Chiplet
- CPO



MEMS VPC



WLCSP Probe Card



Cobra VPC

Advanced Packaging Accelerates Demand for System Level Testing

SLT&SFT

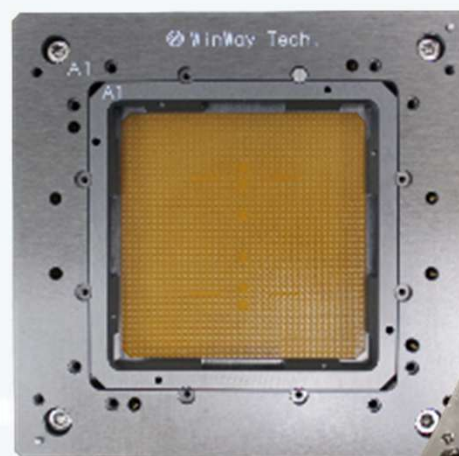
2024-2029 CAGR

More than

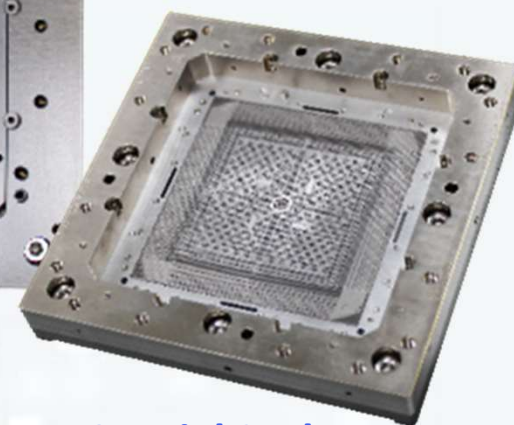
Greater than
industry growth

15%↑

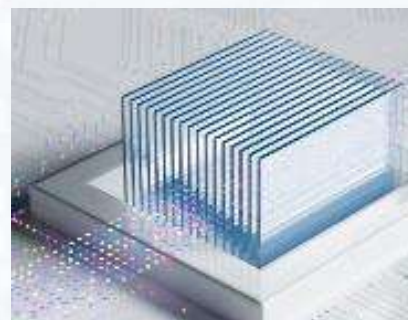
Source : WinWay 2024



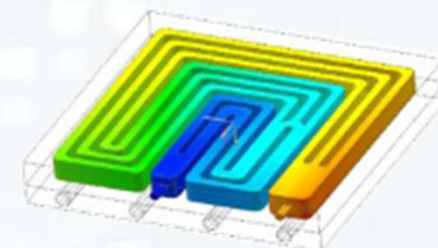
HyperSocket™



Coaxial Socket



Thermal System (Liquid Cooling)



Future Trend for High-Speed Burn-in

Functional Burn-in

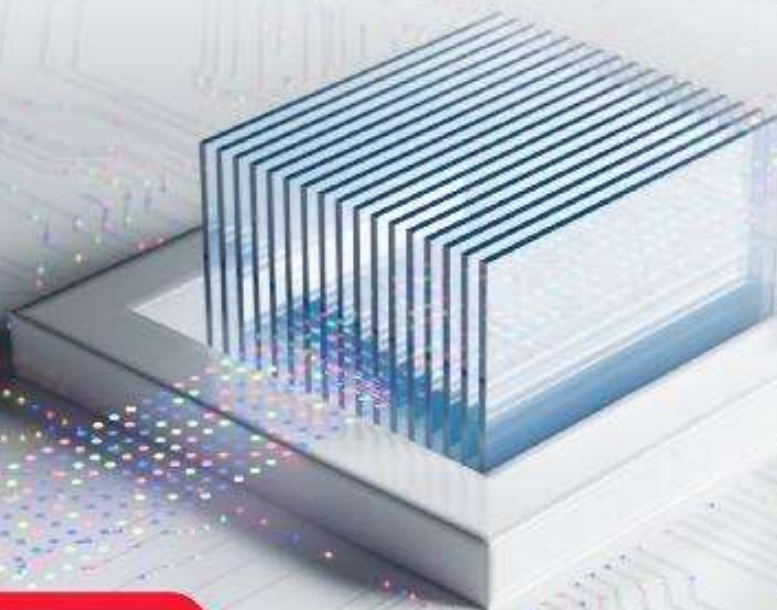
- High Power Burn-In Oven
- System Level Test Burn-In



High Power 1000W

Large Package 120 X 120 mm²

High Speed PCIE Gen5 32Gbps



**Collaborative
Robot**



Automotive



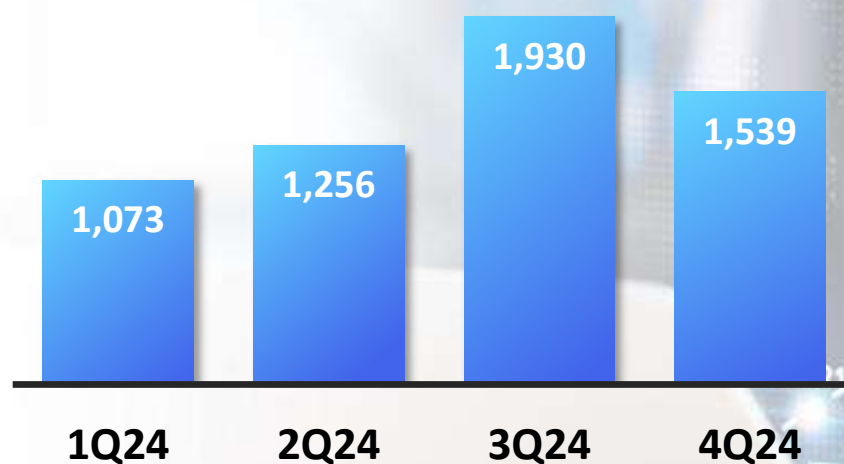
Data Center

03

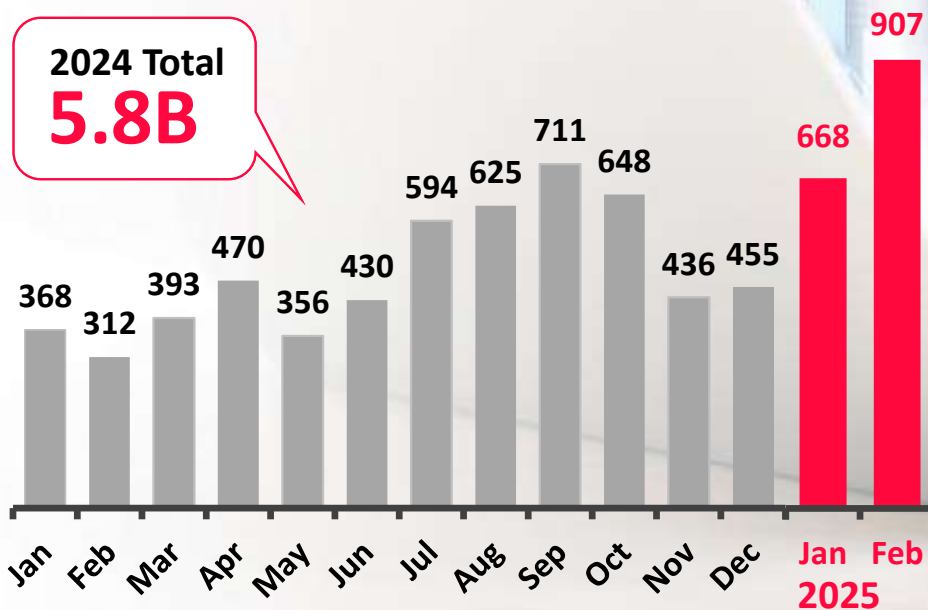
Financial Performance

Revenue Trend

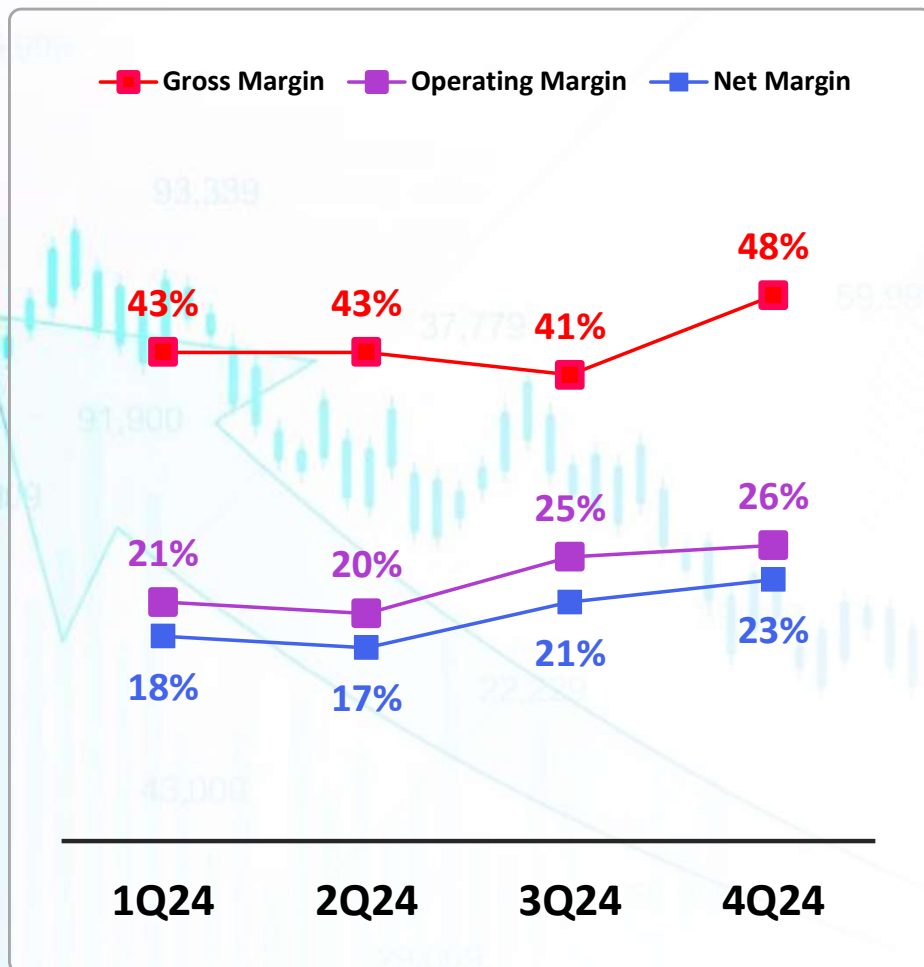
QUARTERLY REVENUE (NTD MILLION)



MONTHLY REVENUE (NTD MILLION)



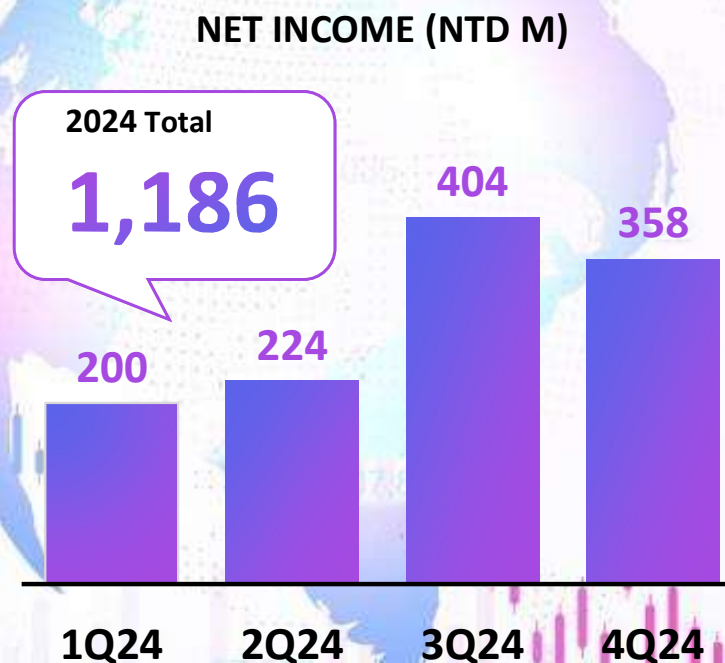
Profitability Trend



2024 EPS
(NT\$) **34.31**

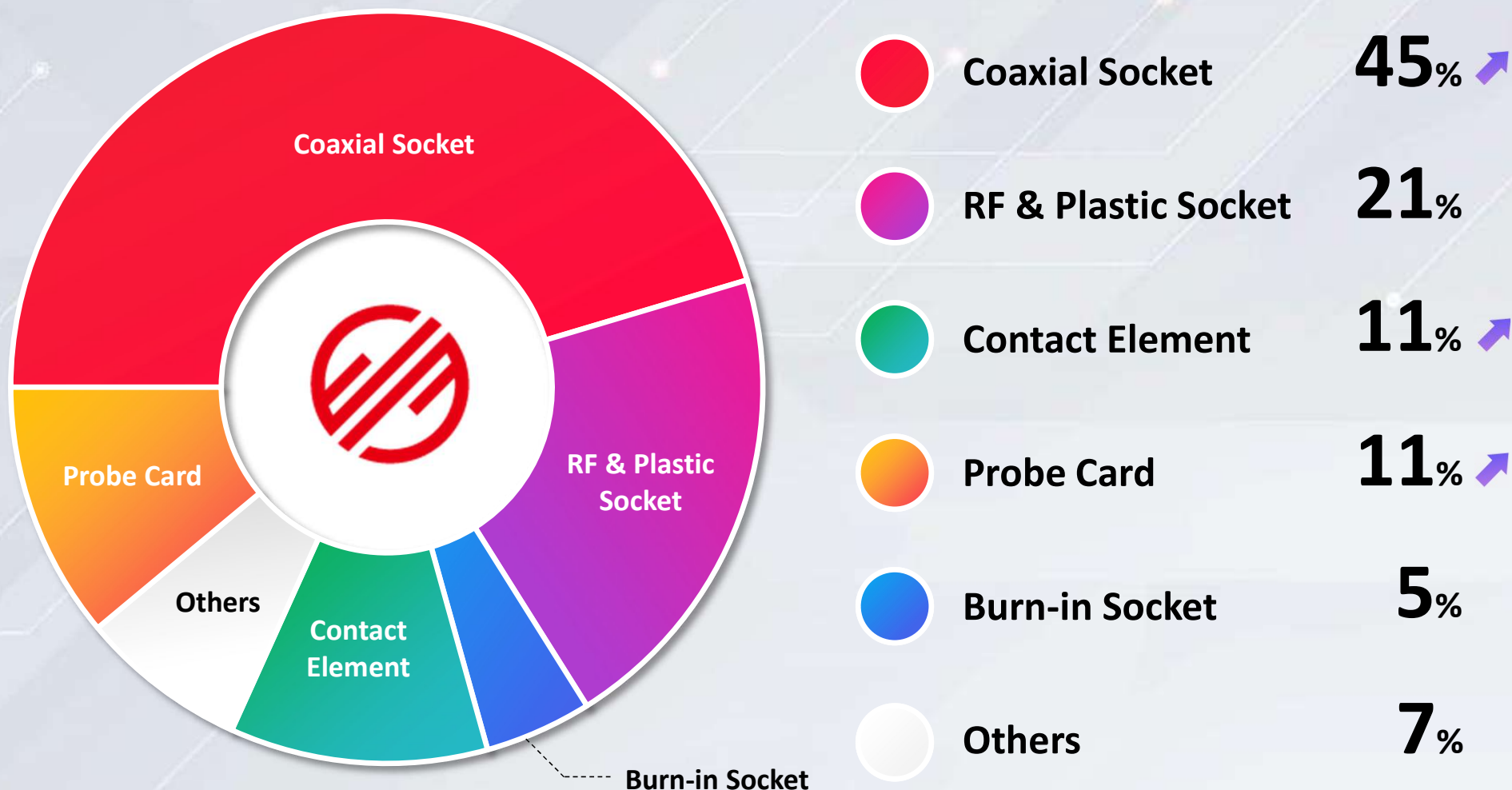
Dividend
25.0

5.81	6.52	11.75	10.23
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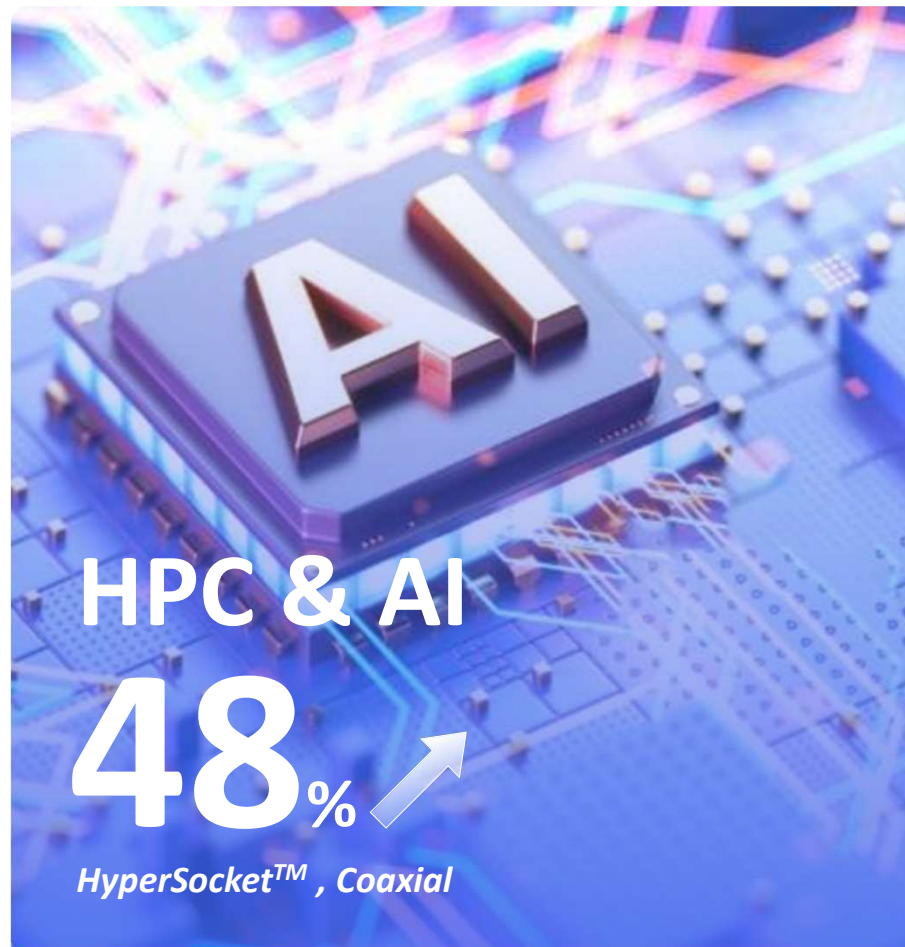
Revenue by Product Mix

(Year 2024)



Revenue by End Market

END MARKET (Year 2024)

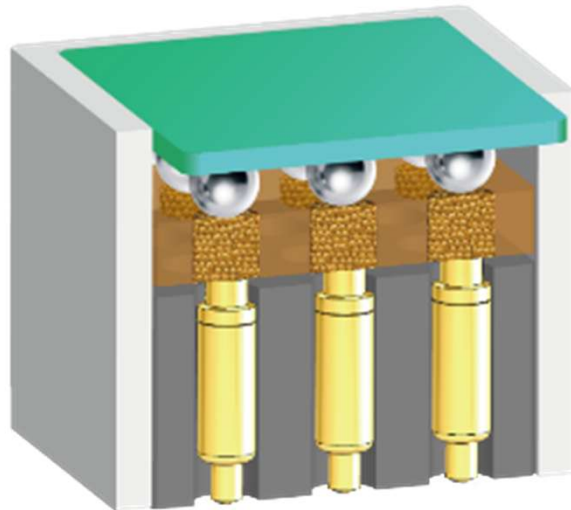


04

R&D Innovation

Best-in-Class Test Socket

WinWay HyperSocket™



- Best solution for high-speed signal
- Well-positioned for larger, more advanced package design
- Superior thermal dissipation for high-current testing

Patent NO.

TWI862047

TWI862191

CN20570508U

Patent Pending

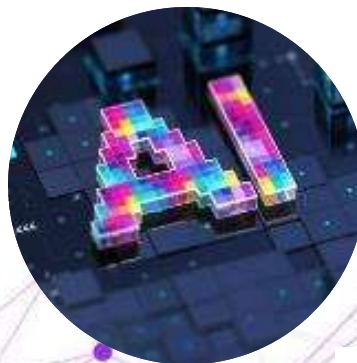
USA

Japan

Korea

Malaysia

AI&HPC



Smartphone



Automotive



SLT

SFT

Co-Packaged Optics Test Solution

Total Solution for CPO



IC Design



Foundry



OSAT

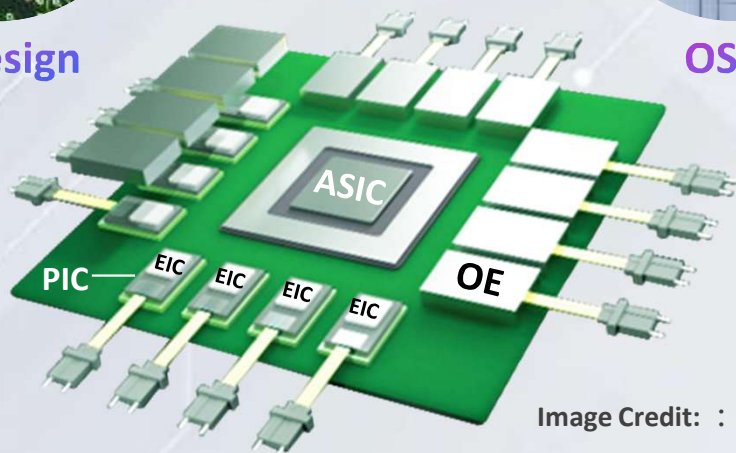
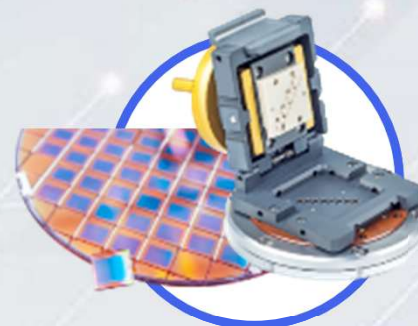
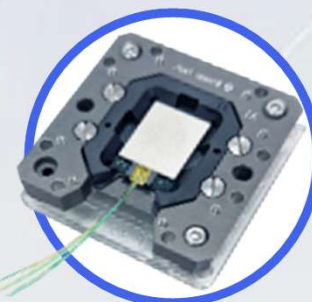


Image Credit: : ASE

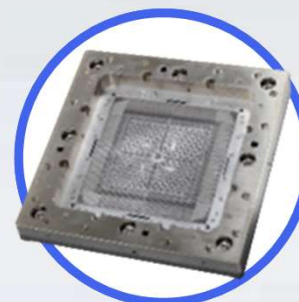
Co-Packaged Optics



WLCSP Fine Pitch Socket

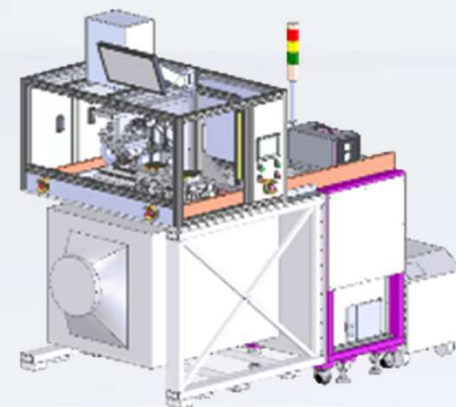


Optical and Electrical Test Socket



Coaxial Socket

Double Sided Probing System



Spring Probe Manufacturing

Socket All in House

Cost Reduction Customer Growth

2025
Demand **8M** / Month

2025
Capacity **4.5M** / Month



SEMICON CHINA

 2025.03.26-28

 **China** / Shanghai New International Expo Centre

SEMICON SEA

 2025.05.20-22

 **Singapore** / Sands Expo and Convention Centre

SWTEST

 2025.06.02-04

 **USA** / Omni La Costa Carlsbad, CA

SHAREHOLDERS' MEETING

 2025.06.19

 **Taiwan** / Zhuang Jing Auditorium, Kaohsiung

Q&A



WinWay

股票代號 **6515**

THANK YOU

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